

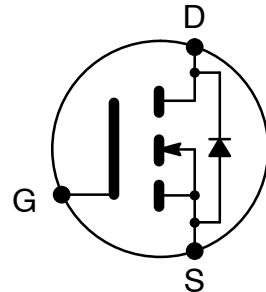


ELECTRONICS, INC.  
44 FARRAND STREET  
BLOOMFIELD, NJ 07003  
(973) 748-5089  
<http://www.nteinc.com>

**NTE2987**  
**Logic Level MOSFET**  
**N-Channel, Enhancement Mode**  
**High Speed Switch**  
**TO220 Type Package**

**Features:**

- Avalanche Rugged Technology
- Logic Level Gate Drive
- $R_{DS(on)} = 0.09 \pm$  Typ. at  $V_{GS} = 5V$
- $+175^{\circ}C$  Operating Temperature
- Fast Switching
- Low Gate Charge
- High Current Capability



**Absolute Maximum Ratings:**

Drain Current, $I_D$ Continuous	
$T_C = +25^{\circ}C$	20A
$T_C = +100^{\circ}C$	14A
Pulsed (Note 1)	80A
Total Power Dissipation ( $T_C = +25^{\circ}C$ ), $P_D$	105W
Derate Above $25^{\circ}C$	0.7W/ $^{\circ}C$
Gate-Source Voltage, $V_{GS}$	$\pm 15V$
Avalanche Current, Repetitive or Non-Repetitive (Note 2), $I_{AR}$	20A
Single Pulsed Avalanche Energy (Note 3), $E_{AS}$	120mJ
Repetitive Avalanche Energy (Note 2), $E_{AR}$	30mJ
Avalanche Current, Repetitive or Non-Repetitive (Note 4), $I_{AR}$	14A
Drain-Source Voltage ( $V_{GS} = 0$ ), $V_{DS}$	100V
Drain-Gate Voltage ( $R_{GS} = 20k\pm$ ), $V_{DGR}$	100V
Operating Junction Temperature, $T_J$	$+175^{\circ}C$
Storage Temperature Range, $T_{stg}$	-65° to $+175^{\circ}C$
Maximum Lead Temperature (During Soldering, 1.6mm from case, 10sec), $T_L$	$+300^{\circ}C$
Thermal Resistance:	
Maximum Junction-to-Case, $R_{thJC}$	1.43 $^{\circ}C/W$
Typical Case-to-Sink (Mounting surface flat, smooth, and greased), $R_{thcs}$	0.5 $^{\circ}C/W$
Maximum Junction-to-Ambient (Free Air Operation), $R_{thJA}$	62.5 $^{\circ}C/W$

Note 1. Pulse width limited by safe operating area.

Note 2. Pulse width limited by  $T_J$  max, Duty Cycle < 1%.

Note 3.  $V_{DD} = 25V$ ,  $I_D = I_{AR}$ , Starting  $T_J = +175^{\circ}C$ .

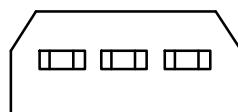
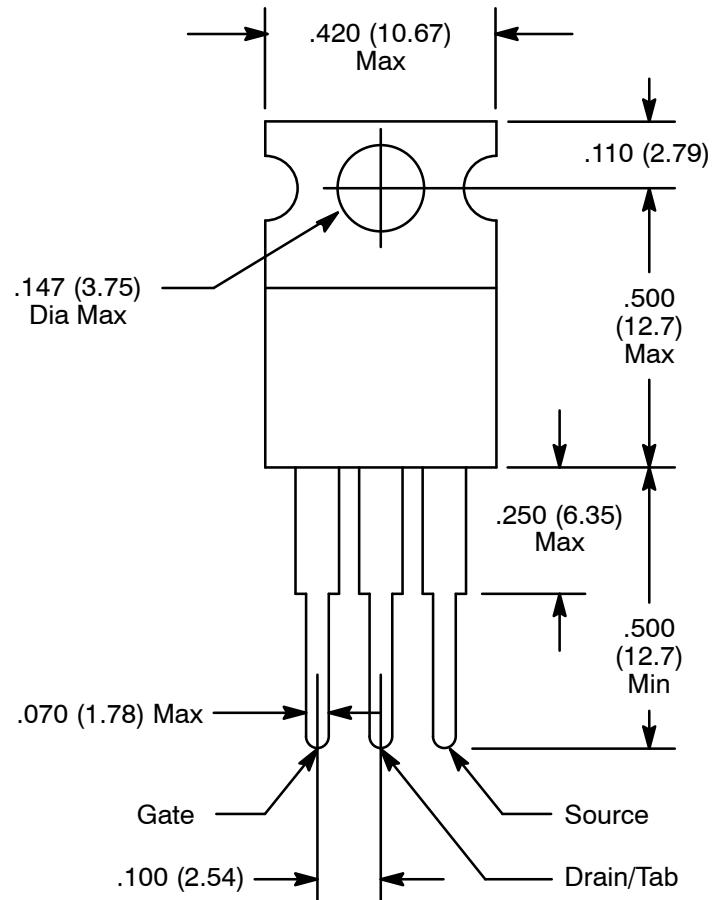
Note 4.  $T_C = +100^{\circ}C$ , Pulse width limited by  $T_J$  max, Duty Cycle < 1%.

**Electrical Characteristics:** ( $T_C = +25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF</b>						
Drain–Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250^\circ\text{A}$	100	–	–	V
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0$	–	–	1	$^\circ\text{A}$
		$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}, T_C = +150^\circ\text{C}$	–	–	10	$^\circ\text{A}$
Gate–Source Leakage Forward	$I_{\text{GSS}}$	$V_{\text{GS}} = 15\text{V}$	–	–	100	nA
Gate–Source Leakage Reverse	$I_{\text{GSS}}$	$V_{\text{GS}} = -15\text{V}$	–	–	-100	nA
<b>ON (Note 5)</b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250^\circ\text{A}$	1.0	1.6	2.5	V
Static Drain–Source ON Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 5\text{V}, I_D = 10\text{A}$	–	0.09	0.12	$\pm$
On-State Drain Current	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} > I_{\text{D}(\text{on})} \times R_{\text{DS}(\text{on})}\text{max}, V_{\text{GS}} = 10\text{V}$	20	–	–	A
<b>Dynamic</b>						
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}} > I_{\text{D}(\text{on})} \times R_{\text{DS}(\text{on})}\text{max}, I_D = 10\text{A},$ Note 5	10	16	–	mhos
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$	–	1200	1500	pF
Output Capacitance	$C_{\text{oss}}$		–	250	350	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		–	60	90	pF
<b>Switching</b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 5\text{V}, I_D = 20\text{A}, V_{\text{DD}} = 80\text{V}$	–	22	30	nC
Gate–Source Charge	$Q_{\text{gs}}$		–	6	–	nC
Gate–Drain (“Miller”) Charge	$Q_{\text{gd}}$		–	12	–	nC
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 10\text{A}, R_G = 50\pm,$ $V_{\text{GS}} = 5\text{V}$	–	50	70	ns
Rise Time	$t_r$		–	140	200	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		–	80	110	ns
Fall Time	$t_f$	$V_{\text{DD}} = 80\text{V}, I_D = 20\text{A}, R_G = 50\pm,$ $V_{\text{GS}} = 5\text{V}$	–	80	110	ns
<b>Source–Drain Diode Ratings and Characteristics</b>						
Continuous Source Current	$I_S$	(Body Diode)	–	–	20	A
Pulse Source Current	$I_{\text{SM}}$	(Body Diode) Note 1	–	–	80	A
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{SD}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$ , Note 5	–	–	1.5	V
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = +150^\circ\text{C}, V_{\text{DD}} = 50\text{V}, I_{\text{SD}} = 20\text{A},$ $dI/dt = 100\text{A}/^\circ\text{s}$	–	130	–	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		–	0.4	–	$^\circ\text{C}$
Reverse Recovery Current	$I_{\text{RRM}}$		–	6	–	A

Note 1. Pulse width limited by safe operating area.

Note 5. Pulse Test: Pulse Width =  $300^\circ\text{s}$ , Duty Cycle = 1.5%.



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